

CLAIMS:

1. A light-emitting semiconductor potting composition comprising

5 (A) 100 parts by weight of an organopolysiloxane having a vinyl group at an end of its molecular chain, represented by the average compositional formula (1):



10 wherein R is a monovalent organic group, at least 5 mol% of R being phenyl, and "a" is a number of 1.5 to 3.0,

(B) an organohydrogenpolysiloxane having at least two hydrogen atoms each directly bonded to a silicon atom in a molecule, represented by the average compositional formula
15 (2):



20 wherein R^1 is a monovalent organic group, b is a positive number of 0.7 to 2.1, c is a positive number of 0.001 to 1.0, and the sum of b+c is 0.8 to 3, in an amount to give 0.7 to 10 silicon atom-bonded hydrogen atoms per vinyl group in component (A),

25 (C) a platinum group metal catalyst in an amount to give 1 to 1,000 ppm of platinum group metal based on the weight of components (A) and (B) combined, and

(D) 0 to 10 parts by weight of an organosilicon compound having an alkoxy group bonded to a silicon atom,

30 the cured product of said composition having a refractive index of 1.41 to 1.56 at 25°C and 589 nm (sodium D line).

2. The composition of claim 1 which is cured into the
35 cured product having a refractive index of 1.43 to 1.55 at 25°C and 589 nm (sodium D line).

3. The composition of claim 1 which is cured into the cured product having a Durometer Type A hardness of up to 75.

4. A light-emitting semiconductor device comprising a ceramic and/or plastic housing defining an open interior and a light-emitting semiconductor member disposed in the housing, the interior of the housing being filled with the potting
5 composition of claim 1 in the cured state.

5. A light-emitting semiconductor device comprising a ceramic and/or plastic housing defining an open interior and a light-emitting semiconductor member disposed on lead
10 electrodes in the housing, the interior of the housing being filled with the potting composition of claim 1 in the cured state.